

(1.27 mm) .050"

LPAM SERIES

IGH-SPEED LOW-PROFILE OPEN-PIN-FIEL

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?LPAM

Insulator Material:

Terminal Material: Copper Alloy Plating:

Au or Šn over 50 μ" (1.27 μm) Ni **Current Rating:**

2.2 A per pin (8 adjacent pins powered) Working Voltage: 250 VAC

RoHS Compliant:

Lead-Free Solderable:

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE (MOQ Required)

- · Tin-Lead Solder Charge
- · Other pins/row and row counts
- · Other Gold plating options

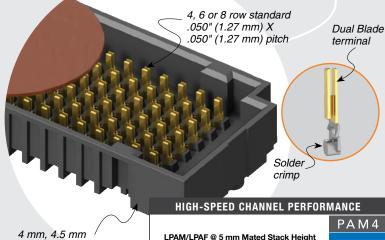
Mates with:

Standoffs:



NO. PINS

PER ROW



LPAM/LPAF @ 5 mm Mated Stack Height

Rating based on Samtec reference channel. For full SI performance data visit Samtec.com or contact SIG@samtec.com

SOLDER

TYPE



-10, -20, -30, -40,

-50(-08 rows only)

-01.0 (1.0 mm) -01.5 = (1.5 mm) .060"

_1 = 10 µ" (0.25 µm) Gold on contact area

Matte Tin on

solder tail

PLATING

OPTION

and 5 mm stack heights

-04 =Four Rows -06

=Six

Rows

-08 =Eight Rows

NO. OF

ROWS

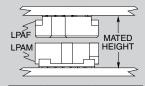
-2 Lead-Free Solder Crimp

Polyimide film Pick &

Place Pad

=Tape & Reel

MATED HEIGHT

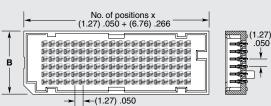


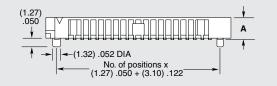
MATED HEIGHT*		
LPAM	LPAF LEAD STYLE	
LEAD STYLE	-03.0	-03.5
-01.0	(4.00) .157	(4.50) .177
-01.5	(4.50) .177	(5.00) .197
*Processing conditions will affect mated height.		

Notes: Patent Pending

Some sizes, styles and options are non-standard, non-returnable.







LEAD STYLE	Α
-01.0	(3.68) .145
-01.5	(4.19) .165